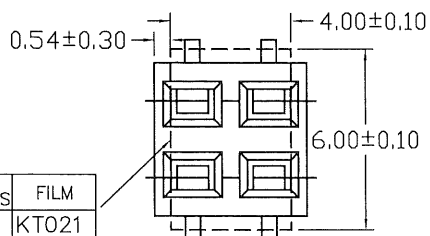
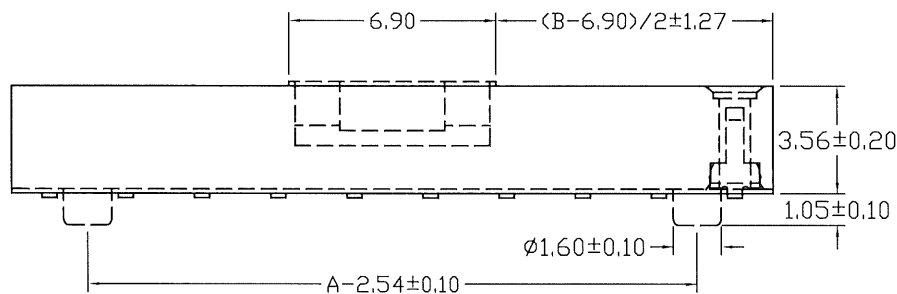
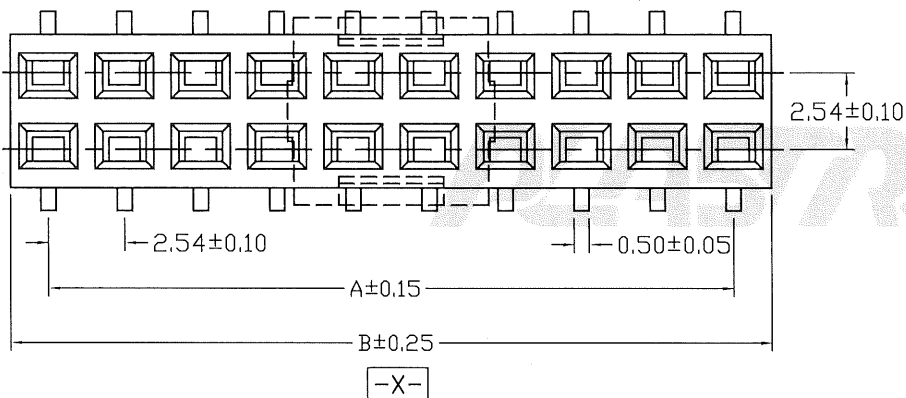


No. of Contacts	DIMENSIONS		W/O PEG	WITH PEG
	A	B		
4	2.54	5.08	○	⊙
6	5.08	7.62	○	○
8	7.62	10.16	○	○
10	10.16	12.70	○	○
12	12.70	15.24	○	○
14	15.24	17.78	○	○
16	17.78	20.32	○	○
18	20.32	22.86	○	○
20	22.86	25.40	○	○
22	25.40	27.94	○	○
24	27.94	30.48	○	○
26	30.48	33.02	○	○
28	33.02	35.56	○	○
30	35.56	38.10	○	○
32	38.10	40.64	○	○
34	40.64	43.18	○	○
36	43.18	45.72	○	○
38	45.72	48.26	○	○
40	48.26	50.80	○	○
42	50.80	53.34	○	○
44	53.34	55.88	○	○
46	55.88	58.42	○	○
48	58.42	60.96	○	○
50	60.96	63.50	○	○
52	63.50	66.04	○	○
54	66.04	68.58	○	○
56	68.58	71.12	○	○
58	71.12	73.66	○	○
60	73.66	76.20	○	○
62	76.20	78.74	○	○
64	78.74	81.28	○	○
66	81.28	83.82	○	○
68	83.82	86.36	○	○
70	86.36	88.90	○	○
72	88.90	91.44	○	○
74	91.44	93.98	○	○
76	93.98	96.52	○	○
78	96.52	99.06	○	○
80	99.06	101.60	○	○

No. of CONTACTS	FILM
4	KTO21



RECOMMENDED PCB LAYOUT
(PCB TOLERANCE ±0.05)



版次	ECN 编码	描述		设计/日期
		改前	改后	
10	EL21040090		Increase heat resistance	苏琴_2021/04/26

NOTES: (UNLESS OTHERWISE SPECIFIED)

- DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M-1994.
- CONTACT RETENTION FORCE: 350g MIN, PER CONTACT.
- INSERTION FORCE: 300g MAX, PER CONTACT.
- WITHDRAW FORCE: 20g MIN, PER CONTACT.
- DURABILITY: 50 CYCLES MIN.
- CURRENT RATING: 3 AMPERE.
- RATING VOLTAGE: 30V AC/DC.
- CONTACT RESISTANCE: 20 m ohms MAX, INITIAL.
- DIELECTRIC WITHSTANDING VOLTAGE: 500V AC rms FOR 1 MINUTE
- INSULATION RESISTANCE: 1000 Megohms MIN.
- OPERATING TEMPERATURE: -40~+105°C.
- FINISH: GOLD PLATED
 - ◎ STANDARD: GOLD FLASH
 - ◎ DUPLEX PLATING: GOLD PLATED ON CONTACT AREA, TIN PLATED ON SOLDER AREA
- CONTACT MATERIAL: PHOSPHOR BRONZE
- ▲ HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, 260C FOR 10 SECONDS, UL 94V-0
- HARMFUL MATERIAL SHOULD BE COMPLIANT TO DOC. "EI-0005" STANDARDS.
- PRODUCT NUMBER MATRIX:

SPAGZ-XX-X-X-*				TUBE (W/O MPAD)
No. of Contacts	□	□	□	B: MPAD+REEL
	□	□	□	E: MPAD+TUBE
	□	□	□	K: REEL
	□	□	□	F: FILM+TUBE
	0	1	2	□: W/O Locating peg
			1	□: With Locating peg

Definition	Code
○ Tin plated:	A
○ Gold plated:	
finish B 5 μ" D 10 μ" E	
15 μ" F 120 μ" G 130 μ" J	
○ Duplex plated:	
finish K 5 μ" M 10 μ" N	
15 μ" P 20 μ" Q 30 μ" U	
○ Standard: B	
○ Prefix "Y" means lead free plating	

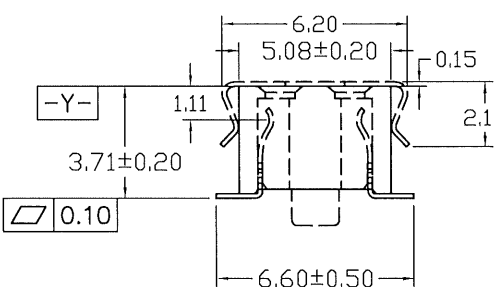


Diagram	Molding description
○	mass production & assemble mold
⊙	sample & assemble mold
⊕	mass production & fix mold
⊗	sample & fix mold



TOLERANCE TABLE		SCALE	DRAWN	DATE	DWG. NO.	TITLE	REV.
X ± 0.30	X° ± 3°	1:1	苏琴	2021/04/26	600-0000-203 PARTS NO. (INTENDED USE) SPAGZ-XX-X-X-*	CUSTOMER DRAWING	10
.X ± 0.25	.X° ± 2°	UNIT mm	苏琴	2021/04/26			SHEET 1/1
.XX ± 0.20		SIZE A4	苏琴	2021/04/26			